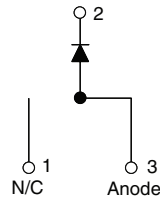


HEXFRED® Ultrafast Soft Recovery Diode, 4 A


D²PAK
FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating temperature
- Compliant to RoHS directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition
- AEC-Q101 qualified


RoHS*
COMPLIANT
HALOGEN FREE
BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA04TB60S is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 4 A continuous current, the HFA04TB60S is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA04TB60S is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

V_R	600 V
V_F at 4 A at 25 °C	1.8 V
$I_{F(AV)}$	4 A
t_{rr} (typical)	17 ns
T_J (maximum)	150 °C
Q_{rr} at 125 °C	40 nC
$di_{(rec)M}/dt$ at 125 °C	280 A/ μ s

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	4	A
Single pulse forward current	I_{FSM}		25	
Maximum repetitive forward current	I_{FRM}		16	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	25	W
		$T_C = 100\text{ °C}$	10	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C

* Pb containing terminations are not RoHS compliant, exemptions may apply

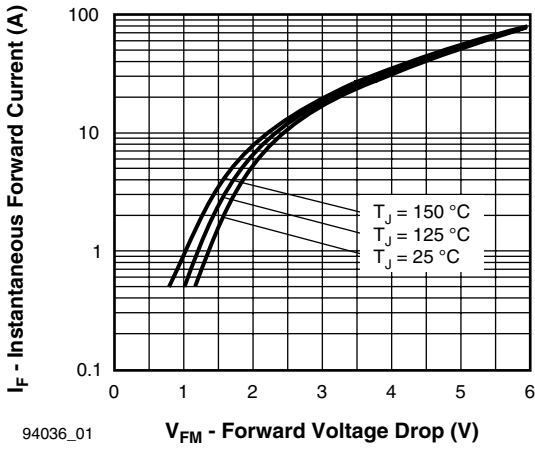
ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	600	-	-	V
Maximum forward voltage	V _{FM}	I _F = 4.0 A	-	1.5	1.8	
		I _F = 8.0 A	-	1.8	2.2	
		I _F = 4.0 A, T _J = 125 °C	-	1.4	1.7	
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	-	0.17	3.0	μA
		T _J = 125 °C, V _R = 0.8 x V _R rated	-	44	300	
Junction capacitance	C _T	V _R = 200 V	-	4.0	8.0	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 6	t _{rr}	I _F = 1.0 A, di _F /dt = 200 A/μs, V _R = 30 V	-	17	-	ns
	t _{rr1}	T _J = 25 °C	-	28	42	
	t _{rr2}	T _J = 125 °C	-	38	57	
Peak recovery current	I _{RRM1}	T _J = 25 °C	-	2.9	5.2	A
	I _{RRM2}	T _J = 125 °C	-	3.7	6.7	
Reverse recovery charge See fig. 7	Q _{rr1}	T _J = 25 °C	-	40	60	nC
	Q _{rr2}	T _J = 125 °C	-	70	105	
Peak rate of fall of recovery current during t _b See fig. 8	di _{(rec)M} /dt1	T _J = 25 °C	-	280	-	A/μs
	di _{(rec)M} /dt2	T _J = 125 °C	-	235	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	5.0	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Marking device		Case style D ² PAK	HFA04TB60S			

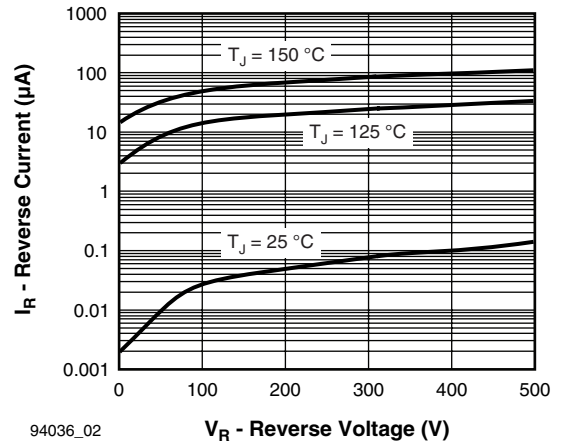
HEXFRED® Ultrafast Soft Recovery Diode, 4 A

Vishay High Power Products



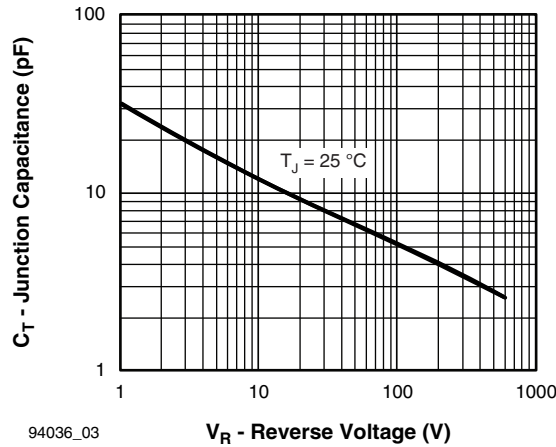
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Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current



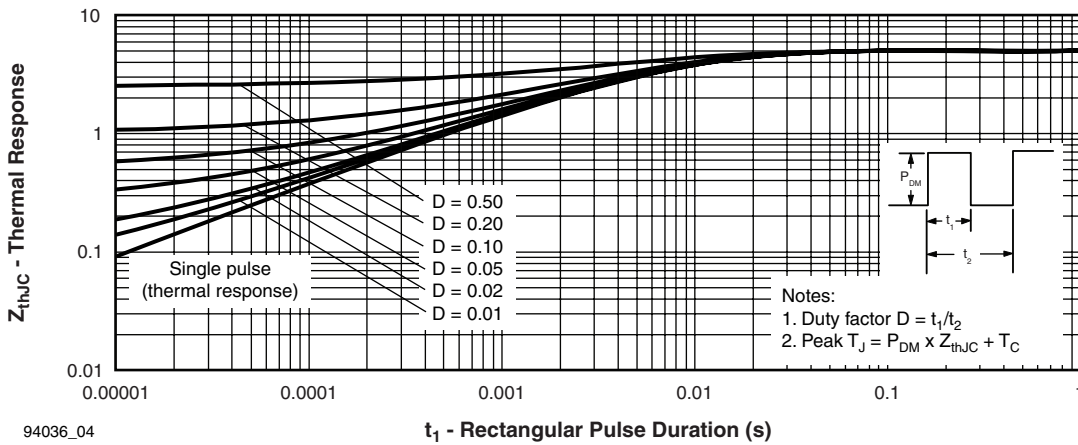
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Fig. 2 - Typical Reverse Current vs. Reverse Voltage



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Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage



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Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

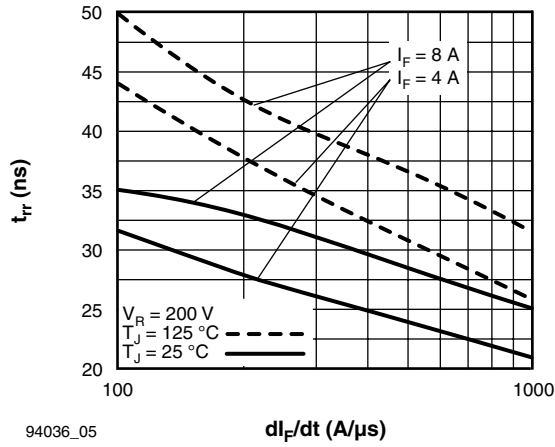


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt

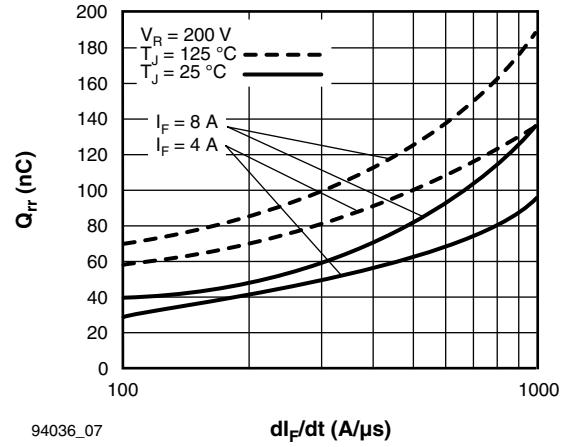


Fig. 7 - Typical Stored Charge vs. dI_F/dt

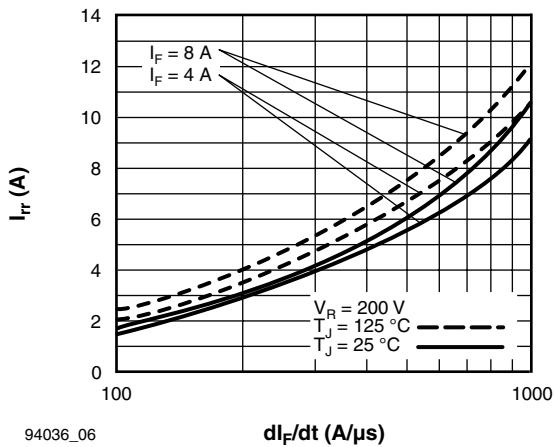


Fig. 6 - Typical Recovery Current vs. dI_F/dt

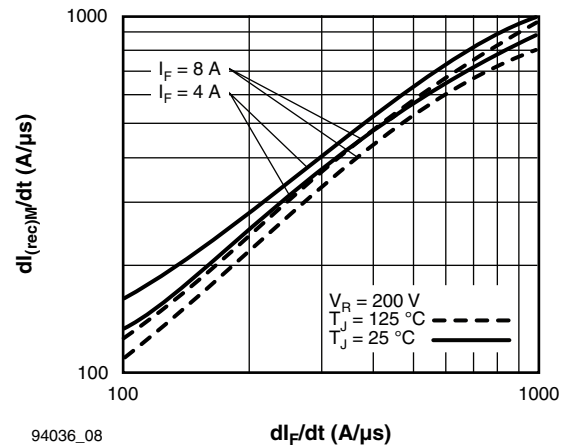


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

HEXFRED®
 Ultrafast Soft Recovery Diode, 4 A

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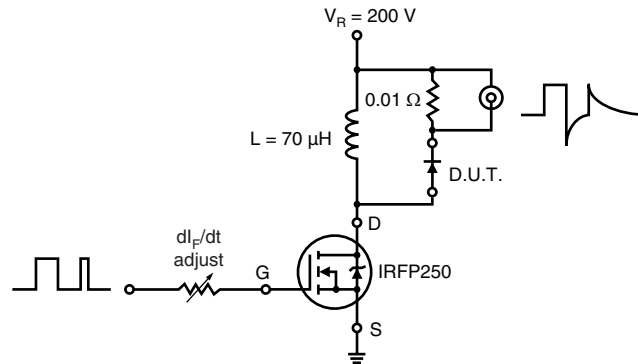
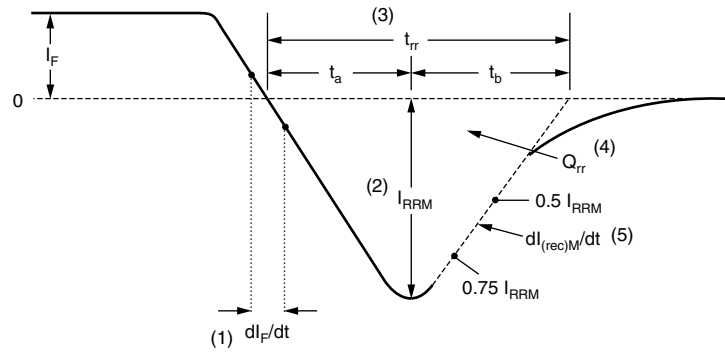


Fig. 9 - Reverse Recovery Parameter Test Circuit


 (1) dl_F/dt - rate of change of current through zero crossing

 (2) I_{RRM} - peak reverse recovery current

 (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.

 (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

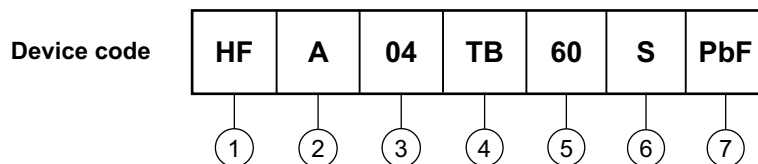
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

 (5) $dl_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - HEXFRED® family
- 2** - Process designator: A = Subs. electron irradiated
B = Subs. platinum
- 3** - Current rating (04 = 4 A)
- 4** - Package outline (TB = TO-220, 2 leads)
- 5** - Voltage rating (60 = 600 V)
- 6** - Configuration (S = SMD)
- 7** -
 - None = Standard production
 - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032



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